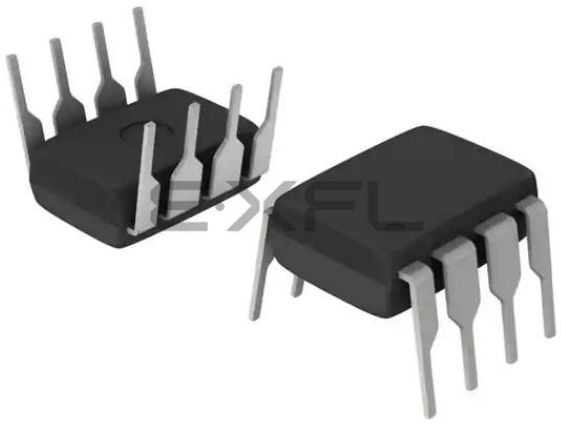

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	3
Program Memory Size	384B (256 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic10f204-e-p

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC10F200/202/204/206 devices can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC10F200/202/204/206 devices use a Harvard architecture in which program and data are accessed on separate buses. This improves bandwidth over traditional von Neumann architectures where program and data are fetched on the same bus. Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 12 bits wide, making it possible to have all single-word instructions. A 12-bit wide program memory access bus fetches a 12-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (33) execute in a single cycle (1 μs @ 4 MHz) except for program branches.

The table below lists program memory (Flash) and data memory (RAM) for the PIC10F200/202/204/206 devices.

TABLE 3-1: PIC10F2XX MEMORY

Device	Memory	
	Program	Data
PIC10F200	256 x 12	16 x 8
PIC10F202	512 x 12	24 x 8
PIC10F204	256 x 12	16 x 8
PIC10F206	512 x 12	24 x 8

The PIC10F200/202/204/206 devices can directly or indirectly address its register files and data memory. All Special Function Registers (SFR), including the PC, are mapped in the data memory. The PIC10F200/202/204/206 devices have a highly orthogonal (symmetrical) instruction set that makes it possible to carry out any operation, on any register, using any addressing mode. This symmetrical nature and lack of “special optimal situations” make programming with the PIC10F200/202/204/206 devices simple, yet efficient. In addition, the learning curve is reduced significantly.

The PIC10F200/202/204/206 devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

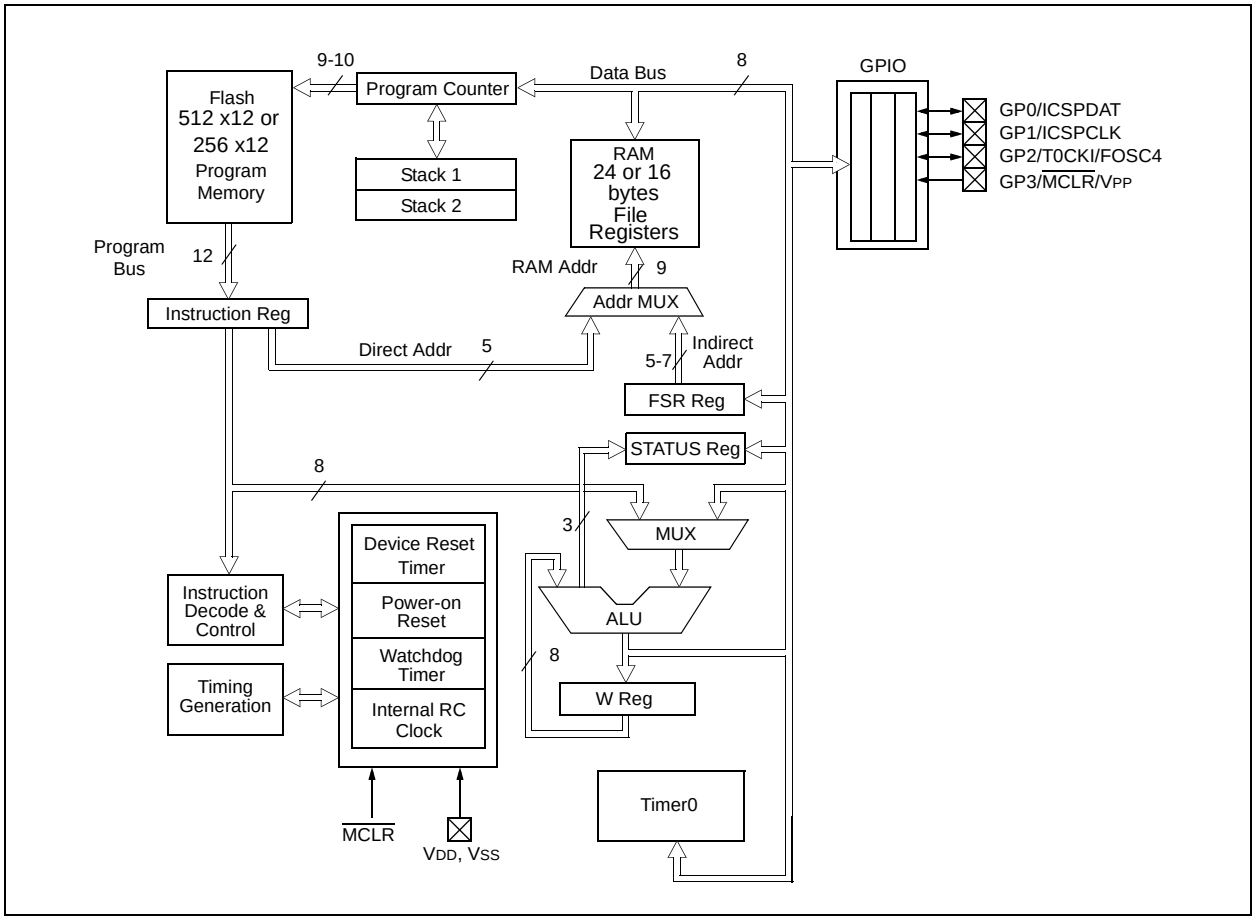
The ALU is 8 bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two’s complement in nature. In two-operand instructions, one operand is typically the W (working) register. The other operand is either a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC) and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBWF and ADDWF instructions for examples.

A simplified block diagram is shown in Figure 3-1 and Figure 3-2, with the corresponding device pins described in Table 3-2.

FIGURE 3-1: PIC10F200/202 BLOCK DIAGRAM

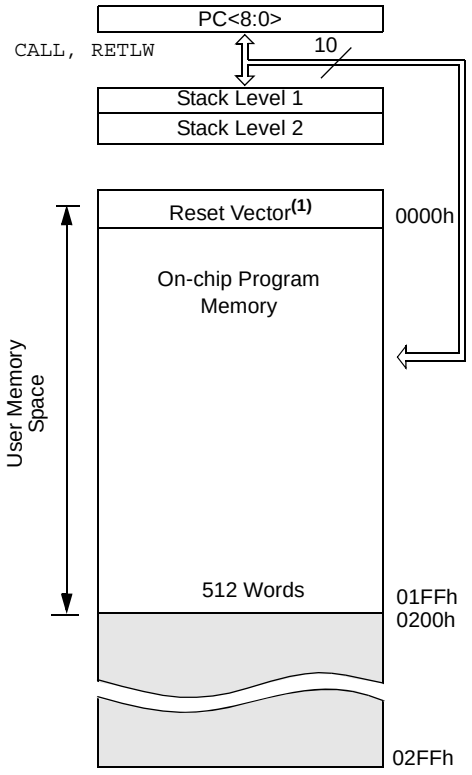


4.2 Program Memory Organization for the PIC10F202/206

The PIC10F202/206 devices have a 10-bit Program Counter (PC) capable of addressing a 1024 x 12 program memory space.

Only the first 512 x 12 (0000h-01FFh) for the PIC10F202/206 are physically implemented (see Figure 4-2). Accessing a location above these boundaries will cause a wraparound within the first 512 x 12 space (PIC10F202/206). The effective Reset vector is at 0000h (see Figure 4-2). Location 01FFh (PIC10F202/206) contains the internal clock oscillator calibration value. This value should never be overwritten.

FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC10F202/206



Note 1: Address 0000h becomes the effective Reset vector. Location 01FFh contains the `MOVLW XX` internal oscillator calibration value.

4.3 Data Memory Organization

Data memory is composed of registers or bytes of RAM. Therefore, data memory for a device is specified by its register file. The register file is divided into two functional groups: Special Function Registers (SFR) and General Purpose Registers (GPR).

The Special Function Registers include the TMR0 register, the Program Counter (PCL), the STATUS register, the I/O register (GPIO) and the File Select Register (FSR). In addition, Special Function Registers are used to control the I/O port configuration and prescaler options.

The General Purpose registers are used for data and control information under command of the instructions.

For the PIC10F200/204, the register file is composed of seven Special Function registers and 16 General Purpose registers (see Figure 4-3 and Figure 4-4).

For the PIC10F202/206, the register file is composed of eight Special Function registers and 24 General Purpose registers (see Figure 4-4).

4.3.1 GENERAL PURPOSE REGISTER FILE

The General Purpose Register file is accessed, either directly or indirectly, through the File Select Register (FSR). See **Section 4.9 “Indirect Data Addressing: INDF and FSR Registers”**.

4.4 STATUS Register

This register contains the arithmetic status of the ALU, the Reset status and the page preselect bit.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS`, will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where u = unchanged).

Therefore, it is recommended that only `BCF`, `BSF` and `MOVWF` instructions be used to alter the STATUS register. These instructions do not affect the Z, DC or C bits from the STATUS register. For other instructions which do affect Status bits, see **Section 10.0 "Instruction Set Summary"**.

REGISTER 4-1: STATUS REGISTER

R/W-0	R/W-0	U-1	R-1	R-1	R/W-x	R/W-x	R/W-x
GPWUF	CWUF(1)	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GPWUF:** GPIO Reset bit
`1` = Reset due to wake-up from Sleep on pin change
`0` = After power-up or other Reset

bit 6 **CWUF:** Comparator Wake-up on Change Flag bit(1)
`1` = Reset due to wake-up from Sleep on comparator change
`0` = After power-up or other Reset conditions.

bit 5 **Reserved:** Do not use. Use of this bit may affect upward compatibility with future products.

bit 4 **$\overline{TO}$:** Time-out bit
`1` = After power-up, `CLRWDT` instruction or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{Borrow}$ bit (for `ADDWF` and `SUBWF` instructions)
`ADDWF`:
`1` = A carry from the 4th low-order bit of the result occurred
`0` = A carry from the 4th low-order bit of the result did not occur
`SUBWF`:
`1` = A borrow from the 4th low-order bit of the result did not occur
`0` = A borrow from the 4th low-order bit of the result occurred

bit 0 **C:** Carry/$\overline{Borrow}$ bit (for `ADDWF`, `SUBWF` and `RRF`, `RLF` instructions)

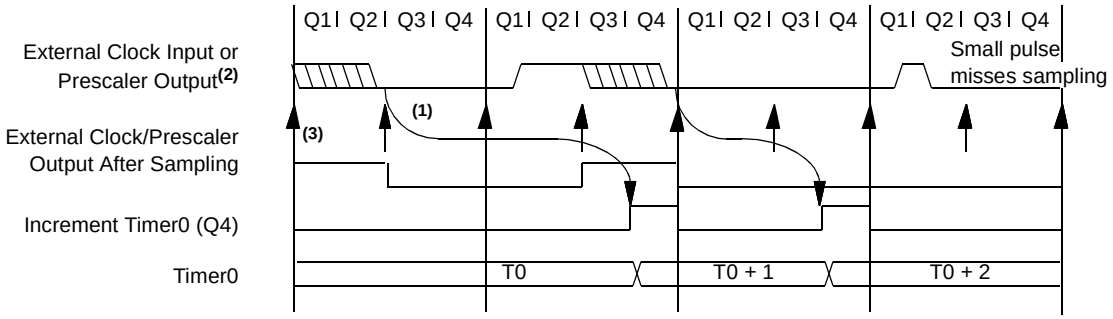
`ADDWF`:	`SUBWF`:	`RRF` or `RLF`:
`1` = A carry occurred	`1` = A borrow did not occur	Load bit with LSb or MSb, respectively
`0` = A carry did not occur	`0` = A borrow occurred	

Note 1: This bit is used on the PIC10F204/206. For code compatibility do not use this bit on the PIC10F200/202.

6.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 6-4 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-4: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3 TOSC to 7 TOSC (Duration of Q = TOSC). Therefore, the error in measuring the interval between two edges on Timer0 input = ±4 TOSC max.

2: External clock if no prescaler selected; prescaler output otherwise.

3: The arrows indicate the points in time where sampling occurs.

6.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module or as a postscaler for the Watchdog Timer (WDT), respectively (see **Section 9.6 "Watchdog Timer (WDT)"**). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet.

Note:	The prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT and vice versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1`, `MOVWF 1`, `BSF 1,x`, etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the WDT. The prescaler is neither readable nor writable. On a Reset, the prescaler contains all '0's.

6.2.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on-the-fly" during program execution). To avoid an unintended device Reset, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to the WDT.

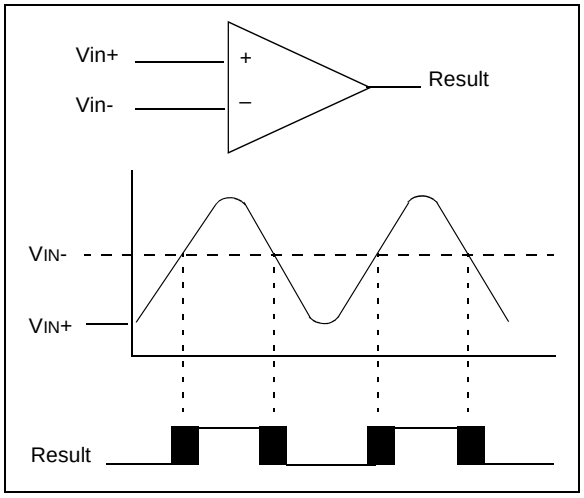
EXAMPLE 6-1: CHANGING PRESCALER (TIMER0 → WDT)

```
CLRWDT              ;Clear WDT
CLRF   TMR0         ;Clear TMR0 & Prescaler
MOVLW  '00xx1111'b  ;These 3 lines (5, 6, 7)
OPTION              ;are required only if
                    ;desired
CLRWDT              ;PS<2:0> are 000 or 001
MOVLW  '00xx1xxx'b  ;Set Postscaler to
OPTION              ;desired WDT rate
```

8.2 Comparator Operation

A single comparator is shown in Figure 8-2 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 8-2 represent the uncertainty due to input offsets and response time. See Table 12-1 for Common Mode Voltage.

FIGURE 8-2: SINGLE COMPARATOR



8.3 Comparator Reference

An internal reference signal may be used depending on the Comparator Operating mode. The analog signal that is present at VIN- is compared to the signal at VIN+ and the digital output of the comparator is adjusted accordingly (Figure 8-2). Please see Table 12-1 for internal reference specifications.

8.4 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output is to have a valid level. If the comparator inputs are changed, a delay must be used to allow the comparator to settle to its new state. Please see Table 12-1 for comparator response time specifications.

8.5 Comparator Output

The comparator output is read through CMCON0 register. This bit is read-only. The comparator output may also be used internally, see Figure 8-1.

Note:	Analog levels on any pin that is defined as a digital input may cause the input buffer to consume more current than is specified.

8.6 Comparator Wake-up Flag

The comparator wake-up flag is set whenever all of the following conditions are met:

- $\overline{CWU}$ = 0 (CMCON0<0>)
- CMCON0 has been read to latch the last known state of the CMPOUT bit (`MOVF CMCON0, W`)
- Device is in Sleep
- The output of the comparator has changed state

The wake-up flag may be cleared in software or by another device Reset.

8.7 Comparator Operation During Sleep

When the comparator is active and the device is placed in Sleep mode, the comparator remains active. While the comparator is powered-up, higher Sleep currents than shown in the power-down current specification will occur. To minimize power consumption while in Sleep mode, turn off the comparator before entering Sleep.

8.8 Effects of a Reset

A Power-on Reset (POR) forces the CMCON0 register to its Reset state. This forces the comparator module to be in the comparator Reset mode. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at Reset time. The comparator will be powered-down during the Reset interval.

8.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 8-3. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 8-3: ANALOG INPUT MODE

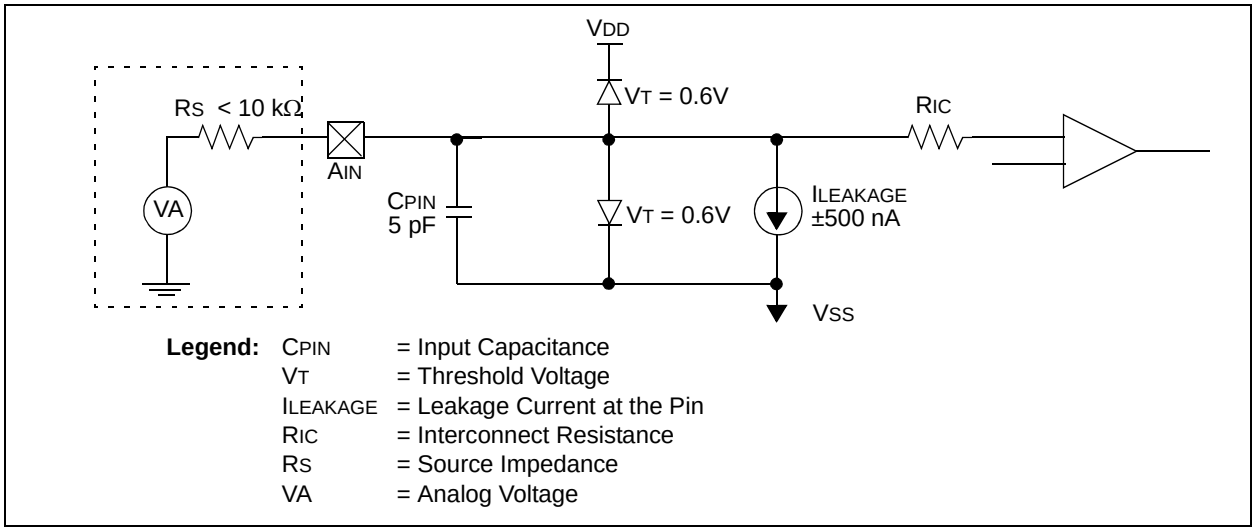


TABLE 8-2: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other Resets
03h	STATUS	GPWUF	CWUF	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	00-1 1xxx	qq0q quuu
07h	CMCON0	CMPOUT	$\overline{COUTEN}$	POL	$\overline{CMPT0CS}$	CMPON	CNREF	CPREF	$\overline{CWU}$	1111 1111	uuuu uuuu
N/A	TRISGPIO	—	—	—	—	I/O Control Register				---- 1111	---- 1111

Legend: x = Unknown, u = Unchanged, – = Unimplemented, read as '0', q = Depends on condition.

TABLE 9-2: RESET CONDITION FOR SPECIAL REGISTERS

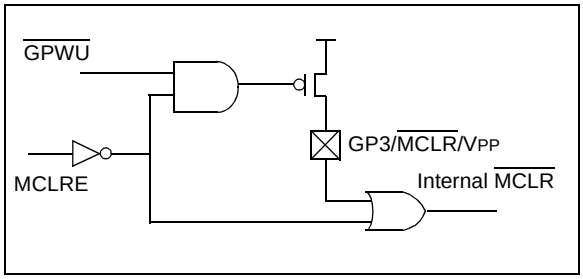
—	STATUS Address: 03h	PCL Address: 02h
Power-on Reset	00-1 1xxx	1111 1111
$\overline{MCLR}$ Reset during normal operation	000u uuuu	1111 1111
$\overline{MCLR}$ Reset during Sleep	0001 0uuu	1111 1111
WDT Reset during Sleep	0000 0uuu	1111 1111
WDT Reset normal operation	0000 uuuu	1111 1111
Wake-up from Sleep on pin change	1001 0uuu	1111 1111
Wake-up from Sleep on comparator change	0101 0uuu	1111 1111

Legend: u = unchanged, x = unknown, – = unimplemented bit, read as '0'.

9.3.1 $\overline{MCLR}$ ENABLE

This Configuration bit, when unprogrammed (left in the '1' state), enables the external $\overline{MCLR}$ function. When programmed, the $\overline{MCLR}$ function is tied to the internal V_{DD} and the pin is assigned to be a I/O. See Figure 9-1.

FIGURE 9-1: $\overline{MCLR}$ SELECT



9.4 Power-on Reset (POR)

The PIC10F200/202/204/206 devices incorporate an on-chip Power-on Reset (POR) circuitry, which provides an internal chip Reset for most power-up situations.

The on-chip POR circuit holds the chip in Reset until V_{DD} has reached a high enough level for proper operation. To take advantage of the internal POR, program the GP3/$\overline{MCLR}$/V_{PP} pin as $\overline{MCLR}$ and tie through a resistor to V_{DD}, or program the pin as GP3. An internal weak pull-up resistor is implemented using a transistor (refer to Table 12-2 for the pull-up resistor ranges). This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for V_{DD} is specified. See **Section 12.0 "Electrical Characteristics"** for details.

When the devices start normal operation (exit the Reset condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the devices must be held in Reset until the operating parameters are met.

A simplified block diagram of the on-chip Power-on Reset circuit is shown in Figure 9-2.

The Power-on Reset circuit and the Device Reset Timer (see **Section 9.5 "Device Reset Timer (DRT)"**) circuit are closely related. On power-up, the Reset latch is set and the DRT is reset. The DRT timer begins counting once it detects $\overline{MCLR}$ to be high. After the time-out period, which is typically 18 ms, it will reset the Reset latch and thus end the on-chip Reset signal.

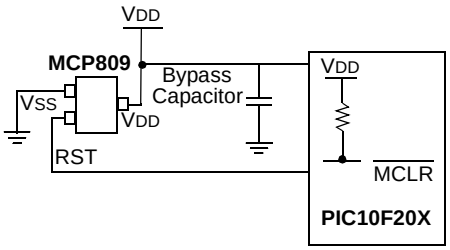
A power-up example where $\overline{MCLR}$ is held low is shown in Figure 9-3. V_{DD} is allowed to rise and stabilize before bringing $\overline{MCLR}$ high. The chip will actually come out of Reset T_{DRT} msec after $\overline{MCLR}$ goes high.

In Figure 9-4, the on-chip Power-on Reset feature is being used ($\overline{MCLR}$ and V_{DD} are tied together or the pin is programmed to be GP3). The V_{DD} is stable before the Start-up Timer times out and there is no problem in getting a proper Reset. However, Figure 9-5 depicts a problem situation where V_{DD} rises too slowly. The time between when the DRT senses that $\overline{MCLR}$ is high and when $\overline{MCLR}$ and V_{DD} actually reach their full value, is too long. In this situation, when the Start-up Timer times out, V_{DD} has not reached the V_{DD} (min) value and the chip may not function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 9-4).

Note:	When the devices start normal operation (exit the Reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Notes AN522 *"Power-up Considerations"*, (DS00522) and AN607 *"Power-up Trouble Shooting"*, (DS00000607).

FIGURE 9-9: BROWN-OUT PROTECTION CIRCUIT 3



Note: This brown-out protection circuit employs Microchip Technology's MCP809 microcontroller supervisor. There are seven different trip point selections to accommodate 5V to 3V systems.

9.9 Power-down Mode (Sleep)

A device may be powered-down (Sleep) and later powered-up (wake-up from Sleep).

9.9.1 SLEEP

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{TO}$ bit (STATUS<4>) is set, the $\overline{PD}$ bit (STATUS<3>) is cleared and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, driving low or high-impedance).

Note: A Reset generated by a WDT time-out does not drive the $\overline{MCLR}$ pin low.

For lowest current consumption while powered-down, the T0CKI input should be at VDD or VSS and the GP3/$\overline{MCLR}$/VPP pin must be at a logic high level if $\overline{MCLR}$ is enabled.

9.9.2 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

1. An external Reset input on GP3/$\overline{MCLR}$/VPP pin, when configured as $\overline{MCLR}$.
2. A Watchdog Timer time-out Reset (if WDT was enabled).
3. A change on input pin GP0, GP1 or GP3 when wake-up on change is enabled.
4. A comparator output change has occurred when wake-up on comparator change is enabled.

These events cause a device Reset. The $\overline{TO}$, $\overline{PD}$ GPWUF and CWUF bits can be used to determine the cause of device Reset. The $\overline{TO}$ bit is cleared if a WDT time-out occurred (and caused wake-up). The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The GPWUF bit indicates a change in state while in Sleep at pins GP0, GP1 or GP3 (since the last file or bit operation on GP port). The CWUF bit indicates a change in the state while in Sleep of the comparator output.

Caution: Right before entering Sleep, read the input pins. When in Sleep, wake-up occurs when the values at the pins change from the state they were in at the last reading. If a wake-up on change occurs and the pins are not read before re-entering Sleep, a wake-up will occur immediately even if no pins change while in Sleep mode.

Note: The WDT is cleared when the device wakes from Sleep, regardless of the wake-up source.

TABLE 10-2: INSTRUCTION SET SUMMARY

Mnemonic, Operands		Description	Cycles	12-Bit Opcode			Status Affected	Notes
				MSb		LSb		
ADDWF	f, d	Add W and f	1	0001	11df	ffff	C, DC, Z	**1, 2, 4**
ANDWF	f, d	AND W with f	1	0001	01df	ffff	Z	**2, 4**
CLRF	f	Clear f	1	0000	011f	ffff	Z	**4**
CLRW	—	Clear W	1	0000	0100	0000	Z	
COMF	f, d	Complement f	1	0010	01df	ffff	Z	
DECF	f, d	Decrement f	1	0000	11df	ffff	Z	**2, 4**
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	0010	11df	ffff	None	**2, 4**
INCF	f, d	Increment f	1	0010	10df	ffff	Z	**2, 4**
INCFSZ	f, d	Increment f, Skip if 0	1(2)	0011	11df	ffff	None	**2, 4**
IORWF	f, d	Inclusive OR W with f	1	0001	00df	ffff	Z	**2, 4**
MOVF	f, d	Move f	1	0010	00df	ffff	Z	**2, 4**
MOVWF	f	Move W to f	1	0000	001f	ffff	None	**1, 4**
NOP	—	No Operation	1	0000	0000	0000	None	
RLF	f, d	Rotate left f through Carry	1	0011	01df	ffff	C	**2, 4**
RRF	f, d	Rotate right f through Carry	1	0011	00df	ffff	C	**2, 4**
SUBWF	f, d	Subtract W from f	1	0000	10df	ffff	C, DC, Z	**1, 2, 4**
SWAPF	f, d	Swap f	1	0011	10df	ffff	None	**2, 4**
XORWF	f, d	Exclusive OR W with f	1	0001	10df	ffff	Z	**2, 4**
BIT-ORIENTED FILE REGISTER OPERATIONS								
BCF	f, b	Bit Clear f	1	0100	bbbf	ffff	None	**2, 4**
BSF	f, b	Bit Set f	1	0101	bbbf	ffff	None	**2, 4**
BTFSC	f, b	Bit Test f, Skip if Clear	1(2)	0110	bbbf	ffff	None	
BTFSS	f, b	Bit Test f, Skip if Set	1(2)	0111	bbbf	ffff	None	
LITERAL AND CONTROL OPERATIONS								
ANDLW	k	AND literal with W	1	1110	kkkk	kkkk	Z	
CALL	k	Call Subroutine	2	1001	kkkk	kkkk	None	**1**
CLRWDT		Clear Watchdog Timer	1	0000	0000	0100	$\overline{TO}$, $\overline{PD}$	
GOTO	k	Unconditional branch	2	101k	kkkk	kkkk	None	
IORLW	k	Inclusive OR literal with W	1	1101	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	1100	kkkk	kkkk	None	
OPTION	—	Load OPTION register	1	0000	0000	0010	None	
RETLW	k	Return, place Literal in W	2	1000	kkkk	kkkk	None	
SLEEP	—	Go into Standby mode	1	0000	0000	0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register	1	0000	0000	0fff	None	**3**
XORLW	k	Exclusive OR literal to W	1	1111	kkkk	kkkk	Z	

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for GOTO. See **Section 4.7 "Program Counter"**.

2: When an I/O register is modified as a function of itself (e.g. MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

3: The instruction TRIS f, where f = 6, causes the contents of the W register to be written to the tri-state latches of PORTB. A '1' forces the pin to a high-impedance state and disables the output buffers.

4: If this instruction is executed on the TMR0 register (and where applicable, d = 1), the prescaler will be cleared (if assigned to TMR0).

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W) + (f) → (dest)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register and register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ANDLW	AND literal with W
Syntax:	[*label*] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W).AND. (k) → (W)
Status Affected:	Z
Description:	The contents of the W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W) .AND. (f) → (dest)
Status Affected:	Z
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	$0 \le f \le 31$ $0 \le b \le 7$
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	$0 \le f \le 31$ $0 \le b \le 7$
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSC	Bit Test f, Skip if Clear
Syntax:	[*label*] BTFSC f,b
Operands:	$0 \le f \le 31$ $0 \le b \le 7$
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', then the next instruction is skipped. If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	$0 \le f \le 31$ $0 \le b < 7$
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a 2-cycle instruction.

CALL	Subroutine Call
Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 255$
Operation:	(PC) + 1→ Top-of-Stack; k → PC<7:0>; (STATUS<6:5>) → PC<10:9>; 0 → PC<8>
Status Affected:	None
Description:	Subroutine call. First, return address (PC + 1) is PUSHed onto the stack. The 8-bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. CALL is a 2-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 31$
Operation:	00h → (f); 1 → Z
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W); 1 → Z
Status Affected:	Z
Description:	The W register is cleared. Zero bit (Z) is set.

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT; 0 → WDT prescaler (if assigned); 1 → $\overline{TO}$; 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	The CLRWDT instruction resets the WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	$(\bar{f}) \rightarrow$ (dest)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

TRIS	Load TRIS Register
Syntax:	[*label*] TRIS f
Operands:	f = 6
Operation:	(W) → TRIS register f
Status Affected:	None
Description:	TRIS register 'f' (f = 6 or 7) is loaded with the contents of the W register

XORLW	Exclusive OR literal with W
Syntax:	[*label*] XORLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the 8-bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	0 ≤ f ≤ 31 d ∈ [0,1]
Operation:	(W) .XOR. (f) → (dest)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

11.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

11.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

12.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... 0 to +6.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} ..... 0 to +13.5V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Max. current out of V_{SS} pin ..... 80 mA
Max. current into V_{DD} pin ..... 80 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Max. output current sunk by any I/O pin ..... 25 mA
Max. output current sourced by any I/O pin ..... 25 mA
Max. output current sourced by I/O port ..... 75 mA
Max. output current sunk by I/O port ..... 75 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

†NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.1 DC Characteristics: PIC10F200/202/204/206 (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +85°C (industrial)				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.0		5.5	V	See Figure 12-1
D002	VDR	**RAM Data Retention Voltage(2)**	1.5*	—	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	
D010	IDD	**Supply Current(3)**					
			— —	175 0.63	275 1.1	µA mA	VDD = 2.0V VDD = 5.0V
D020	IPD	**Power-down Current(4)**					
			— —	0.1 0.35	1.2 2.4	µA µA	VDD = 2.0V VDD = 5.0V
D022	IWDT	**WDT Current(5)**					
			— —	1.0 7	3 16	µA µA	VDD = 2.0V VDD = 5.0V
D023	ICMP	**Comparator Current(5)**					
			— —	12 44	23 80	µA µA	VDD = 2.0V VDD = 5.0V
D024	IVREF	**Internal Reference Current(5,6)**					
			—	85 175	115 195	µA µA	VDD = 2.0V VDD = 5.0V

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ.") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active operation mode are:
All I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode.

4: Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS.

5: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled.

6: Measured with the comparator enabled.

12.2 DC Characteristics: PIC10F200/202/204/206 (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +125°C (extended)				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.0		5.5	V	See Figure 12-1
D002	VDR	**RAM Data Retention Voltage(2)**	1.5*		—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	Vss	—	V	
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	
D010	IDD	**Supply Current(3)**					
			— —	175 0.63	275 1.1	μA mA	VDD = 2.0V VDD = 5.0V
D020	IPD	**Power-down Current(4)**					
			— —	0.1 0.35	9 15	μA μA	VDD = 2.0V VDD = 5.0V
D022	IWDT	**WDT Current(5)**					
			— —	1.0 7	18 22	μA μA	VDD = 2.0V VDD = 5.0V
D023	ICMP	**Comparator Current(5)**					
			— —	12 42	27 85	μA μA	VDD = 2.0V VDD = 5.0V
D024	VREF	**Internal Reference Current(5,6)**					
			—	85 175	120 200	μA μA	VDD = 2.0V VDD = 5.0V

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ.") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active operation mode are: All I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode.

4: Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS.

5: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled.

6: Measured with the Comparator enabled.

TABLE 12-4: RESET, WATCHDOG TIMER AND DEVICE RESET TIMER – PIC10F200/202/204/206

AC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in **Section 12.1 "DC Characteristics: PIC10F200/202/204/206 (Industrial)"**				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
30	TMC_L	$\overline{MCLR}$ Pulse Width (low)	2* 5*	— —	— —	µs µs	VDD = 5V, -40°C to +85°C VDD = 5.0V
31	TWDT	Watchdog Timer Time-out Period (no prescaler)	10 10	16 16	29 31	ms ms	VDD = 5.0V (industrial) VDD = 5.0V (extended)
32	TDRT	Device Reset Timer Period (standard)	10 10	16 16	29 31	ms ms	VDD = 5.0V (industrial) VDD = 5.0V (extended)
34	TIOZ	I/O High-impedance from $\overline{MCLR}$ low	—	—	2*	µs	

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ.") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 12-4: TIMER0 CLOCK TIMINGS – PIC10F200/202/204/206

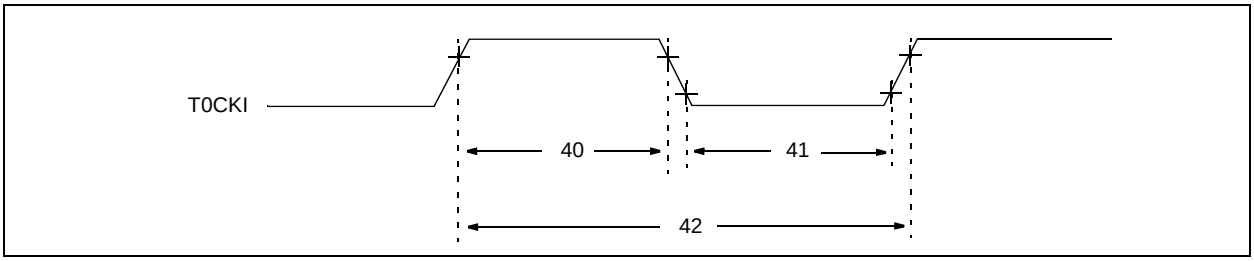


TABLE 12-5: TIMER0 CLOCK REQUIREMENTS – PIC10F200/202/204/206

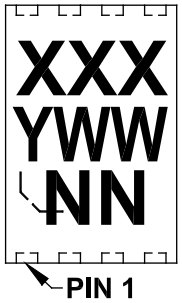
AC CHARACTERISTICS				Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in **Section 12.1 "DC Characteristics: PIC10F200/202/204/206 (Industrial)"**.				
Param. No.	**Sym.**	**Characteristic**		**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		20 or $\frac{T_{CY} + 40*}{N}$	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ.") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Package Marking Information (Continued)

8-Lead DFN (2x3x0.9 mm)



Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

***** Standard PIC® device marking consists of Microchip part number, year code, week code, and traceability code. For PIC device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

TABLE 14-1: 8-LEAD 2x3 DFN (MC) PACKAGE TOP MARKING

Part Number	Marking
PIC10F200-I/MC	BA0
PIC10F200-E/MC	BB0
PIC10F202-I/MC	BC0
PIC10F202-E/MC	BD0
PIC10F204-I/MC	BE0
PIC10F204-E/MC	BF0
PIC10F206-I/MC	BG0
PIC10F206-E/MC	BH0

TABLE 14-2: 6-LEAD SOT-23 (OT) PACKAGE TOP MARKING

Part Number	Marking
PIC10F200-I/OT	00NN
PIC10F200-E/OT	00NN
PIC10F202-I/OT	02NN
PIC10F202-E/OT	02NN
PIC10F204-I/OT	04NN
PIC10F204-E/OT	04NN
PIC10F206-I/OT	06NN
PIC10F206-E/OT	06NN

Note: NN represents the alphanumeric traceability code.